

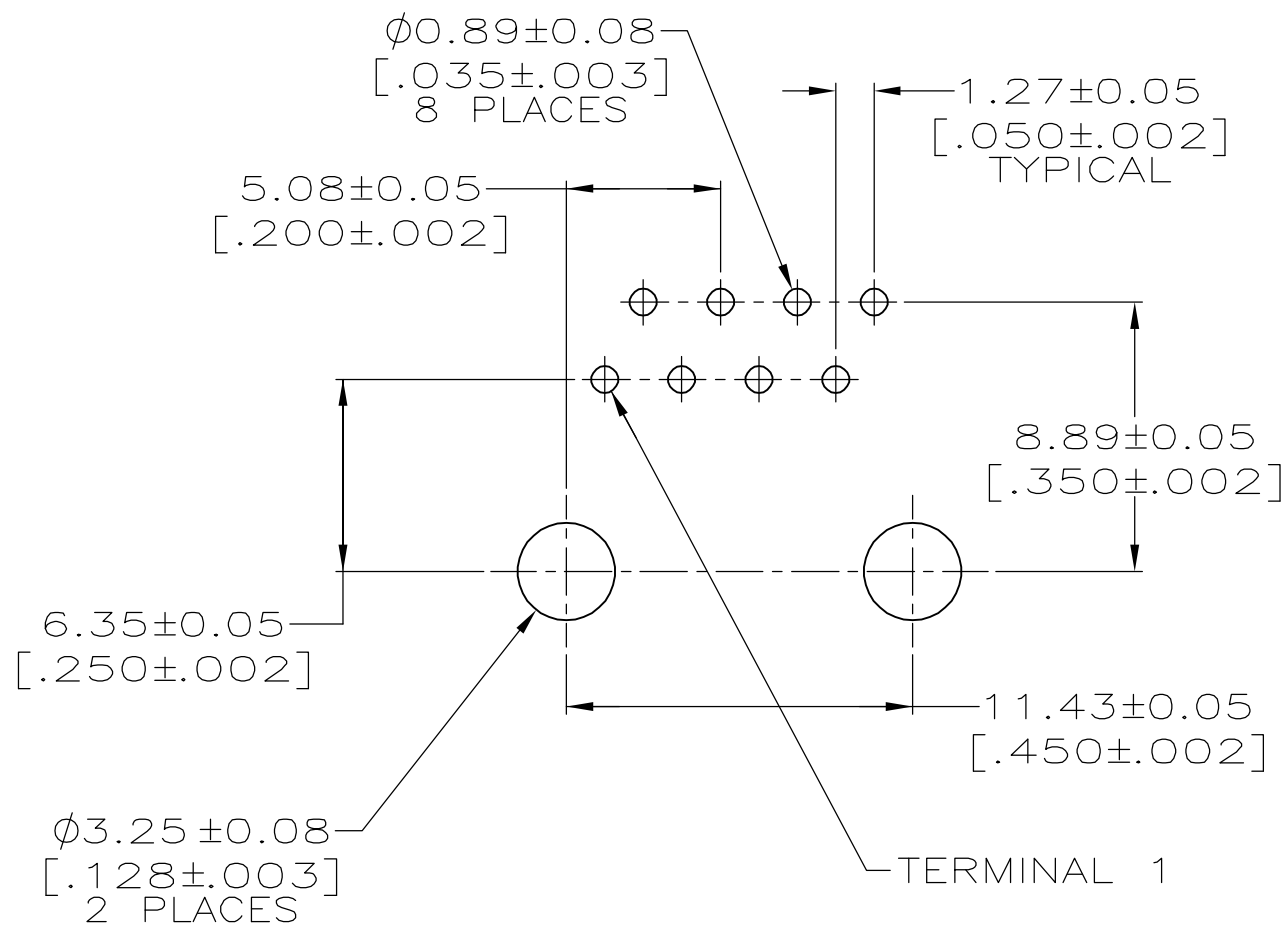
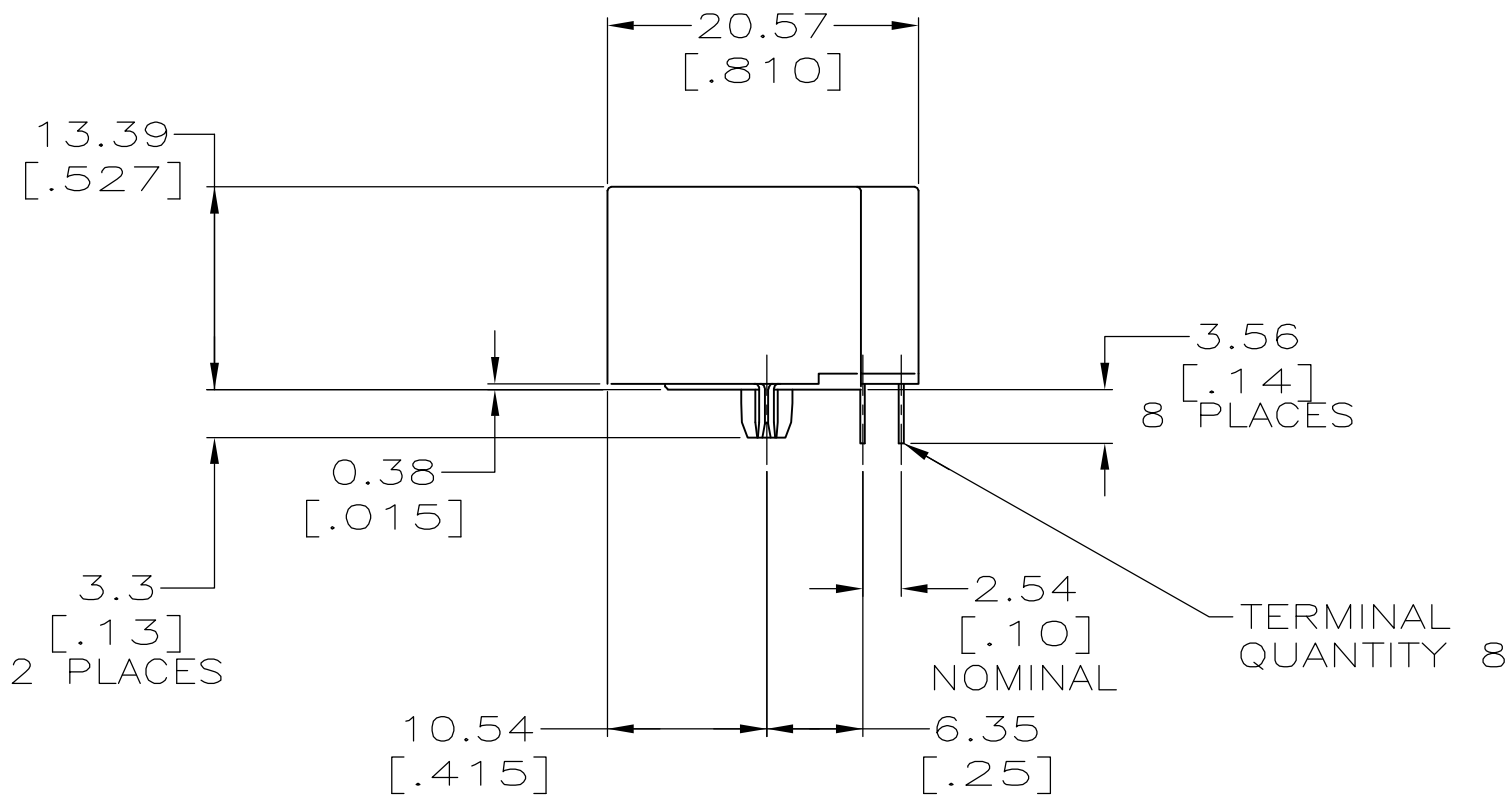
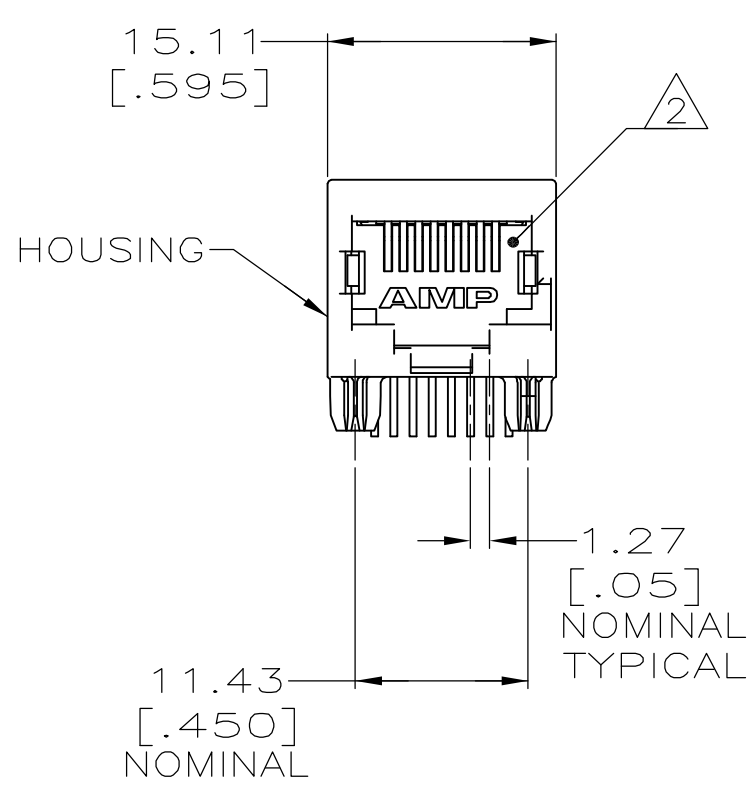
LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
AA	22		A	REV PER EC 0S11-0201-04	08JUN2005	LV	SF

D

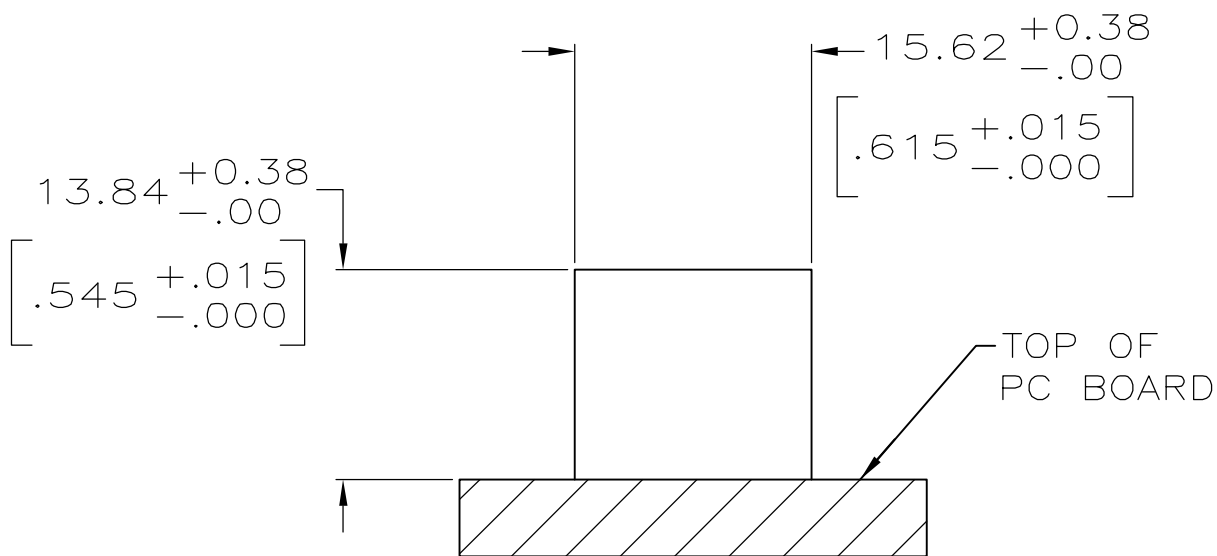
C

B

A

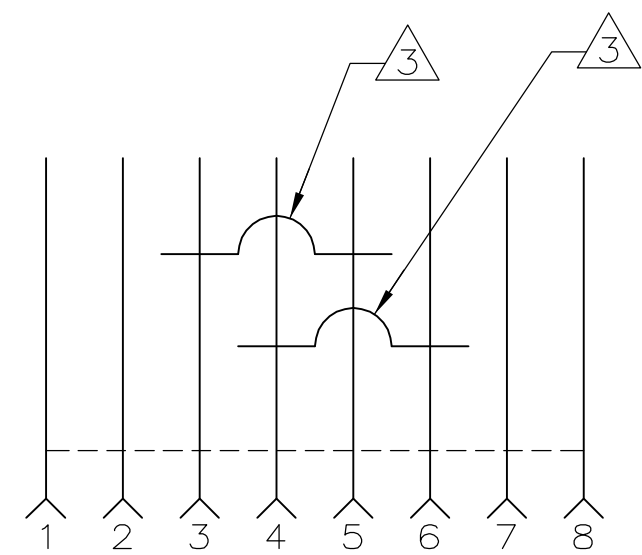


SUGGESTED PC BOARD LAYOUT
COMPONENT SIDE
SCALE 4:1



SUGGESTED PANEL CUTOUT

- 1 MATERIAL: HOUSING – HIGH TEMPERATURE NYLON, BLACK, UL 94V-0, IR REFLOW COMPATIBLE. TERMINALS – 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27 μ m[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81 μ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] MINIMUM THICK NICKEL UNDERPLATE.
- 2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3 SHORT IS REMOVED BY INSERTION OF MODULAR PLUG.



SHORTING FEATURE

5569972

B

A

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN L. VARELA – 08JUN2005	tyco Electronics Tyco Electronics Corporation Harrisburg, PA 17105-3608			
DIMENSIONS: mm [inches]		CHK J. WESTMAN 08JUN2005				
		APVD S. FLICKINGER 08JUN2005	NAME			
		PRODUCT SPEC 108-1163	MODULAR JACK ASSEMBLY, 8 POSITION, KEYED, RIGHT ANGLE, LOW PROFILE, SHORTING, TOKEN RING			
MATERIAL		APPLICATION SPEC 114-2048				
FINISH		WEIGHT -	SIZE A2	CAGE CODE 00779	DRAWING NO C=5569972	RESTRICTED TO -
		CUSTOMER DRAWING	SCALE 2:1	SHEET 1	OF 1	REV A